2013311-1 × OBSOLETE

RAYCHEM RVS

TE Internal #: 2013311-1

TE Internal Description: SEMI-HARD TRAY DDR3 204P 9.2H RVS

View on TE.com >



Connectors > Socket Connectors > Memory Sockets > SO DIMM Sockets



DRAM Type: Double Data Rate (DDR) 3

Stack Height: 9.2 mm [.362 in]

Module Orientation: Right Angle

Number of Positions: 204

Centerline (Pitch): .6 mm [.024 in]

Features

Product Type Features

Product Type Features	
Connector & Contact Terminates To	Printed Circuit Board
DRAM Type	Double Data Rate (DDR) 3
Configuration Features	
Number of Bays	2
Number of Keys	1
Number of Rows	2
Module Orientation	Right Angle
Number of Positions	204
Electrical Characteristics	
DRAM Voltage	1.5 V
Signal Characteristics	
SGRAM Voltage	1.5 V
Body Features	
Latch Plating Material	Tin
Latch Material	Stainless Steel
Module Key Type	SGRAM
Ejector Type	Locking

Both Ends

Contact Features

Ejector Location



Memory Socket Type	Memory Card
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Gold
Contact Mating Area Plating Material	Gold Flash
Termination Features	
Insertion Style	Cam-In
Termination Method to PCB	Surface Mount
Mechanical Attachment	
PCB Mount Retention Type	Solder Peg
Mating Alignment Type	Reverse Keying
PCB Mount Retention	With
Housing Features	
Housing Material	High Temperature Thermoplastic
Housing Color	Black
Centerline (Pitch)	.6 mm[.024 in]
Dimensions	
Stack Height	9.2 mm[.362 in]
Row-to-Row Spacing	8.2 mm[.322 in]
Industry Standards	
UL Flammability Rating	UL 94V-0
Packaging Features	

Product Compliance

Packaging Method

Packaging Quantity

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Not Yet Reviewed
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUN 2018 (191)

20

Semi-Hard Tray Assembly



Does not contain REACH SVHC

Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per
	homogenous material. Also BFR/CFR/PVC
	Free

Solder Process Capability

Reflow solder capable to 245°C

Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Also in the Series | RAYCHEM RVS



Joints & Splices(4)



RJ45 Connectors(1)



SD Card Connectors(2)



SO DIMM Sockets(13)

Customers Also Bought























Documents

CAD Files

Customer View Model

ENG_CVM_CVM_2013311-1_C.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_2013311-1_C.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_2013311-1_C.3d_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

Product Specifications

Product Specification

English